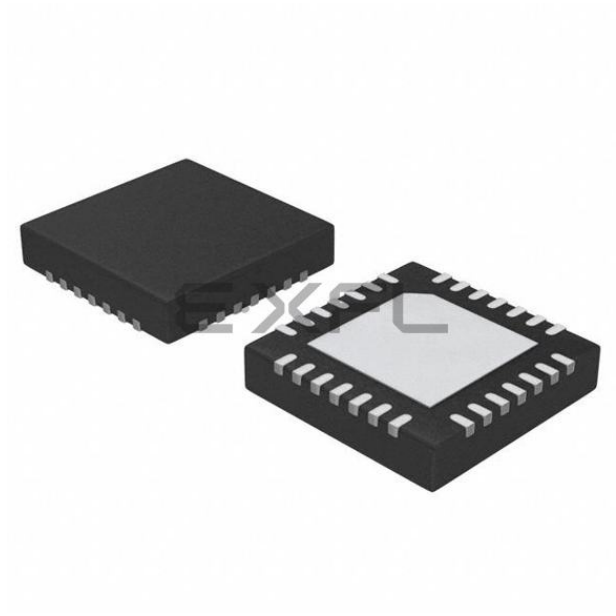

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VFQFN Exposed Pad
Supplier Device Package	28-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16kl402-e-mq

1.2 Other Special Features

- **Communications:** The PIC24F16KL402 family incorporates multiple serial communication peripherals to handle a range of application requirements. The MSSP module implements both SPI and I^2C™ protocols, and supports both Master and Slave modes of operation for each. Devices also include one of two UARTs with built-in IrDA® encoders/decoders.
- **Analog Features:** Select members of the PIC24F16KL402 family include a 10-bit A/D Converter module. The A/D module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, as well as faster sampling speeds.
  The comparator modules are configurable for a wide range of operations and can be used as either a single or double comparator module.

1.3 Details on Individual Family Members

Devices in the PIC24F16KL402 family are available in 14-pin, 20-pin and 28-pin packages. The general block diagram for all devices is shown in Figure 1-1.

The PIC24F16KL402 family may be thought of as four different device groups, each offering a slightly different set of features. These differ from each other in multiple ways:

- The size of the Flash program memory
- The presence and size of data EEPROM
- The presence of an A/D Converter and the number of external analog channels available
- The number of analog comparators
- The number of general purpose timers
- The number and type of CCP modules (i.e., CCP vs. ECCP)
- The number of serial communications modules (both MSSPs and UARTs)

The general differences between the different sub-families are shown in Table 1-1. The feature sets for specific devices are summarized in Table 1-2 and Table 1-3.

A list of the individual pin features available on the PIC24F16KL402 family devices, sorted by function, is provided in Table 1-4 (for PIC24FXXKL40X/30X devices) and Table 1-5 (for PIC24FXXKL20X/10X devices). Note that these tables show the pin location of individual peripheral features and not how they are multiplexed on the same pin. This information is provided in the pinout diagrams in the beginning of this data sheet. Multiplexed features are sorted by the priority given to a feature, with the highest priority peripheral being listed first.

TABLE 1-1: FEATURE COMPARISON FOR PIC24F16KL402 FAMILY GROUPS

Device Group	Program Memory (bytes)	Data EEPROM (bytes)	Timers (8/16-bit)	CCP and ECCP	Serial (MSSP/ UART)	A/D (channels)	Comparators
PIC24FXXKL10X	4K	—	1/2	2/0	1/1	—	1
PIC24FXXKL20X	8K	—	1/2	2/0	1/1	7 or 12	1
PIC24FXXKL30X	8K	256	2/2	2/1	2/2	—	2
PIC24FXXKL40X	8K or 16K	512	2/2	2/1	2/2	12	2

3.2 CPU Control Registers

REGISTER 3-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	DC
bit 15							bit 8

R/W-0(1)	R/W-0(1)	R/W-0(1)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2)	IPL1(2)	IPL0(2)	RA	N	OV	Z	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **DC:** ALU Half Carry/Borrow bit
- 1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
- 0 = No carry-out from the 4th or 8th low-order bit of the result has occurred

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level (IPL) Status bits(1,2)
- 111 = CPU Interrupt Priority Level is 7 (15); user interrupts disabled
- 110 = CPU Interrupt Priority Level is 6 (14)
- 101 = CPU Interrupt Priority Level is 5 (13)
- 100 = CPU Interrupt Priority Level is 4 (12)
- 011 = CPU Interrupt Priority Level is 3 (11)
- 010 = CPU Interrupt Priority Level is 2 (10)
- 001 = CPU Interrupt Priority Level is 1 (9)
- 000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
- 1 = REPEAT loop in progress
- 0 = REPEAT loop not in progress

bit 3 **N:** ALU Negative bit
- 1 = Result was negative
- 0 = Result was non-negative (zero or positive)

bit 2 **OV:** ALU Overflow bit
- 1 = Overflow occurred for signed (2's complement) arithmetic in this arithmetic operation
- 0 = No overflow has occurred

bit 1 **Z:** ALU Zero bit
- 1 = An operation, which effects the Z bit, has set it at some time in the past
- 0 = The most recent operation, which effects the Z bit, has cleared it (i.e., a non-zero result)

bit 0 **C:** ALU Carry/$\overline{\text{Borrow}}$ bit
- 1 = A carry-out from the Most Significant bit (MSb) of the result occurred
- 0 = No carry-out from the Most Significant bit (MSb) of the result occurred

Note 1: The IPL Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

2: The IPL Status bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL when IPL3 = 1.

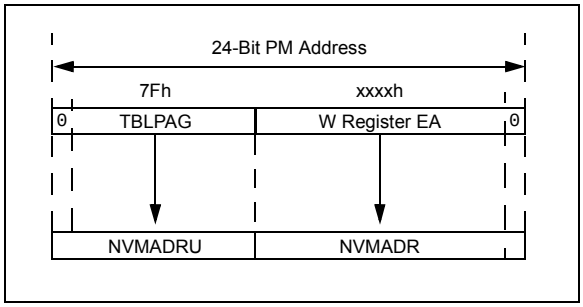
6.3 NVM Address Register

As with Flash program memory, the NVM Address Registers, NVMADRU and NVMADR, form the 24-bit Effective Address (EA) of the selected row or word for data EEPROM operations. The NVMADRU register is used to hold the upper 8 bits of the EA, while the NVMADR register is used to hold the lower 16 bits of the EA. These registers are not mapped into the Special Function Register (SFR) space; instead, they directly capture the EA<23:0> of the last Table Write instruction that has been executed and selects the data EEPROM row to erase. Figure 6-1 depicts the program memory EA that is formed for programming and erase operations.

Like program memory operations, the Least Significant bit (LSb) of NVMADR is restricted to even addresses. This is because any given address in the data EEPROM space consists of only the lower word of the program memory width; the upper word, including the uppermost "phantom byte", is unavailable. This means that the LSb of a data EEPROM address will always be '0'.

Similarly, the Most Significant bit (MSb) of NVMADRU is always '0', since all addresses lie in the user program space.

FIGURE 6-1: DATA EEPROM ADDRESSING WITH TBLPAG AND NVM ADDRESS REGISTERS



6.4 Data EEPROM Operations

The EEPROM block is accessed using Table Read and Table Write operations, similar to those used for program memory. The TBLWTH and TBLRDH instructions are not required for data EEPROM operations since the memory is only 16 bits wide (data on the lower address is valid only). The following programming operations can be performed on the data EEPROM:

- Erase one, four or eight words
- Bulk erase the entire data EEPROM
- Write one word
- Read one word

Note: Unexpected results will be obtained if the user attempts to read the EEPROM while a programming or erase operation is underway.

The C30 C compiler includes library procedures to automatically perform the Table Read and Table Write operations, manage the Table Pointer and write buffers, and unlock and initiate memory write sequences. This eliminates the need to create assembler macros or time critical routines in C for each application.

The library procedures are used in the code examples detailed in the following sections. General descriptions of each process are provided for users who are not using the C30 compiler libraries.

7.4.2 DETECTING BOR

When BOR is enabled, the BOR bit (RCON<1>) is always reset to '1' on any BOR or POR event. This makes it difficult to determine if a BOR event has occurred just by reading the state of BOR alone. A more reliable method is to simultaneously check the state of both POR and BOR. This assumes that the POR and BOR bits are reset to '0' in the software, immediately after any POR event. If the BOR bit is '1' while POR is '0', it can be reliably assumed that a BOR event has occurred.

Note: Even when the device exits from Deep Sleep mode, both the POR and BOR are set.

7.4.3 DISABLING BOR IN SLEEP MODE

When BOREN<1:0> = 10, BOR remains under hardware control and operates as previously described. However, whenever the device enters Sleep mode, BOR is automatically disabled. When the device returns to any other operating mode, BOR is automatically re-enabled.

This mode allows for applications to recover from brown-out situations, while actively executing code when the device requires BOR protection the most. At the same time, it saves additional power in Sleep mode by eliminating the small incremental BOR current.

8.0 INTERRUPT CONTROLLER

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Interrupt Controller, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Interrupts"** (DS39707).

The PIC24F interrupt controller reduces the numerous peripheral interrupt request signals to a single interrupt request signal to the CPU. It has the following features:

- Up to eight processor exceptions and software traps
- Seven user-selectable priority levels
- Interrupt Vector Table (IVT) with up to 118 vectors
- Unique vector for each interrupt or exception source
- Fixed priority within a specified user priority level
- Alternate Interrupt Vector Table (AIVT) for debug support
- Fixed interrupt entry and return latencies

8.1 Interrupt Vector Table (IVT)

The IVT is shown in Figure 8-1. The IVT resides in the program memory, starting at location, 000004h. The IVT contains 126 vectors, consisting of eight non-maskable trap vectors, plus up to 118 sources of interrupt. In general, each interrupt source has its own vector. Each interrupt vector contains a 24-bit wide address. The value programmed into each interrupt vector location is the starting address of the associated Interrupt Service Routine (ISR).

Interrupt vectors are prioritized in terms of their natural priority; this is linked to their position in the vector table. All other things being equal, lower addresses have a higher natural priority. For example, the interrupt associated with vector 0 will take priority over interrupts at any other vector address.

PIC24F16KL402 family devices implement 32 non-maskable traps and unique interrupts; these are summarized in Table 8-1 and Table 8-2.

8.1.1 ALTERNATE INTERRUPT VECTOR TABLE (AIVT)

The Alternate Interrupt Vector Table (AIVT) is located after the IVT, as shown in Figure 8-1. Access to the AIVT is provided by the ALTIVT control bit (INTCON2<15>). If the ALTIVT bit is set, all interrupt and exception processes will use the alternate vectors instead of the default vectors. The alternate vectors are organized in the same manner as the default vectors.

The AIVT supports emulation and debugging efforts by providing a means to switch between an application and a support environment without requiring the interrupt vectors to be reprogrammed. This feature also enables switching between applications for evaluation of different software algorithms at run time. If the AIVT is not needed, the AIVT should be programmed with the same addresses used in the IVT.

8.2 Reset Sequence

A device Reset is not a true exception, because the interrupt controller is not involved in the Reset process. The PIC24F devices clear their registers in response to a Reset, which forces the Program Counter (PC) to zero. The microcontroller then begins program execution at location, 000000h. The user programs a `GOTO` instruction at the Reset address, which redirects the program execution to the appropriate start-up routine.

Note:	Any unimplemented or unused vector locations in the IVT and AIVT should be programmed with the address of a default interrupt handler routine that contains a `RESET` instruction.

REGISTER 8-9: IFS4: INTERRUPT FLAG STATUS REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	HLVDIF
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	U2ERIF(1)	U1ERIF	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **HLVDIF:** High/Low-Voltage Detect Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7-3 **Unimplemented:** Read as '0'

bit 2 **U2ERIF:** UART2 Error Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **U1ERIF:** UART1 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **Unimplemented:** Read as '0'

Note 1: This bit is unimplemented on PIC24FXXKL10X and PIC24FXXKL20X devices.

REGISTER 8-10: IFS5: INTERRUPT FLAG STATUS REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ULPWUIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as '0'

bit 0 **ULPWUIF:** Ultra Low-Power Wake-up Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 7 **CLKLOCK:** Clock Selection Lock Enable bit
If FSCM is Enabled (FCKSM1 = 1):
1 = Clock and PLL selections are locked
0 = Clock and PLL selections are not locked and may be modified by setting the OSWEN bit
If FSCM is Disabled (FCKSM1 = 0):
Clock and PLL selections are never locked and may be modified by setting the OSWEN bit.

bit 6 **Unimplemented:** Read as '0'

bit 5 **LOCK:** PLL Lock Status bit(2)
1 = PLL module is in lock or the PLL module start-up timer is satisfied
0 = PLL module is out of lock, the PLL start-up timer is running or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit
1 = FSCM has detected a clock failure
0 = No clock failure has been detected

bit 2 **SOSCDRV**: Secondary Oscillator Drive Strength bit(3)
1 = High-power SOSC circuit is selected
0 = Low/high-power select is done via the SOSCSRC Configuration bit

bit 1 **SOSCEN:** 32 kHz Secondary Oscillator (SOSC) Enable bit
1 = Enables secondary oscillator
0 = Disables secondary oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Initiates an oscillator switch to the clock source specified by the NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Reset values for these bits are determined by the FNOSC<2:0> Configuration bits.
2: Also resets to '0' during any valid clock switch or whenever a non-PLL Clock mode is selected.
3: When SOSC is selected to run from a digital clock input rather than an external crystal (SOSCSRC = 0), this bit has no effect.

9.4 Clock Switching Operation

With few limitations, applications are free to switch between any of the four clock sources (POSC, SOSC, FRC and LPRC) under software control and at any time. To limit the possible side effects that could result from this flexibility, PIC24F devices have a safeguard lock built into the switching process.

Note:	The Primary Oscillator mode has three different submodes (XT, HS and EC), which are determined by the POSCMDx Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch between the different primary submodes without reprogramming the device.

9.4.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the FOSC Configuration register must be programmed to '0'. (Refer to **Section 23.0 "Special Features"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and FSCM function are disabled; this is the default setting.

The NOSCx control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSCx bits (OSCCON<14:12>) will reflect the clock source selected by the FNOSCx Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled; it is held at '0' at all times.

9.4.2 OSCILLATOR SWITCHING SEQUENCE

At a minimum, performing a clock switch requires this basic sequence:

1. If desired, read the COSCx bits (OSCCON<14:12>) to determine the current oscillator source.
2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
3. Write the appropriate value to the NOSCx bits (OSCCON<10:8>) for the new oscillator source.
4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
5. Set the OSWEN bit to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically, as follows:

1. The clock switching hardware compares the COSCx bits with the new value of the NOSCx bits. If they are the same, then the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.
2. If a valid clock switch has been initiated, the LOCK (OSCCON<5>) and CF (OSCCON<3>) bits are cleared.
3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware will wait until the OST expires. If the new source is using the PLL, then the hardware waits until a PLL lock is detected (LOCK = 1).
4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSCx bits value is transferred to the COSCx bits.
6. The old clock source is turned off at this time, with the exception of LPRC (if WDT or FSCM, with LPRC as a clock source, are enabled) or SOSC (if SOSCEN remains enabled).

Note 1:	The processor will continue to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.
2:	Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

REGISTER 9-4: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROEN	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROEN:** Reference Oscillator Output Enable bit
1 = Reference oscillator is enabled on REFO pin
0 = Reference oscillator is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Output Stop in Sleep bit
1 = Reference oscillator continues to run in Sleep
0 = Reference oscillator is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Primary oscillator is used as the base clock(1)
0 = System clock is used as the base clock; the base clock reflects any clock switching of the device

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divisor Select bits
1111 = Base clock value divided by 32,768
1110 = Base clock value divided by 16,384
1101 = Base clock value divided by 8,192
1100 = Base clock value divided by 4,096
1011 = Base clock value divided by 2,048
1010 = Base clock value divided by 1,024
1001 = Base clock value divided by 512
1000 = Base clock value divided by 256
0111 = Base clock value divided by 128
0110 = Base clock value divided by 64
0101 = Base clock value divided by 32
0100 = Base clock value divided by 16
0011 = Base clock value divided by 8
0010 = Base clock value divided by 4
0001 = Base clock value divided by 2
0000 = Base clock value

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The crystal oscillator must be enabled using the FOSC<2:0> bits; the crystal maintains the operation in Sleep mode.

14.0 TIMER3 MODULE

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Timers, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Timers"** (DS39704).

The Timer3 timer/counter modules incorporate these features:

- Software-selectable operation as a 16-bit timer or counter
- One 16-bit readable and writable Timer Value register
- Selectable clock source (internal or external) with device clock, SOSC or LPRC oscillator options
- Interrupt-on-overflow
- Multiple timer gating options, including:
  - User-selectable gate sources and polarity
  - Gate/toggle operation
  - Single Pulse (One-Shot) mode
- Module Reset on ECCP Special Event Trigger

The Timer3 module is controlled through the T3CON register (Register 14-1). A simplified block diagram of the Timer3 module is shown in Figure 14-1.

The FOSC clock source should not be used with the ECCP capture/compare features. If the timer will be used with the capture or compare features, always select one of the other timer clocking options.

FIGURE 14-1: TIMER3 BLOCK DIAGRAM

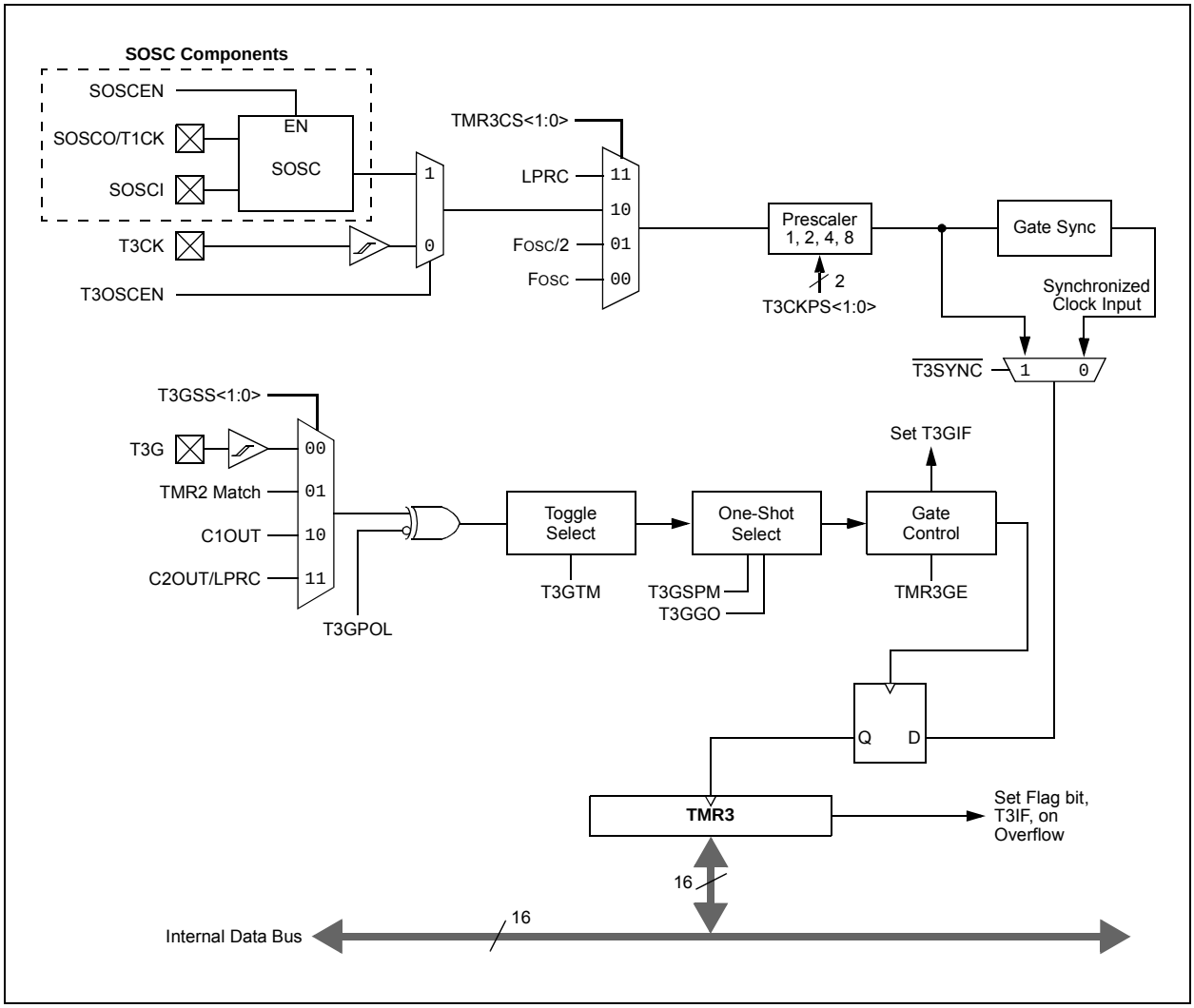
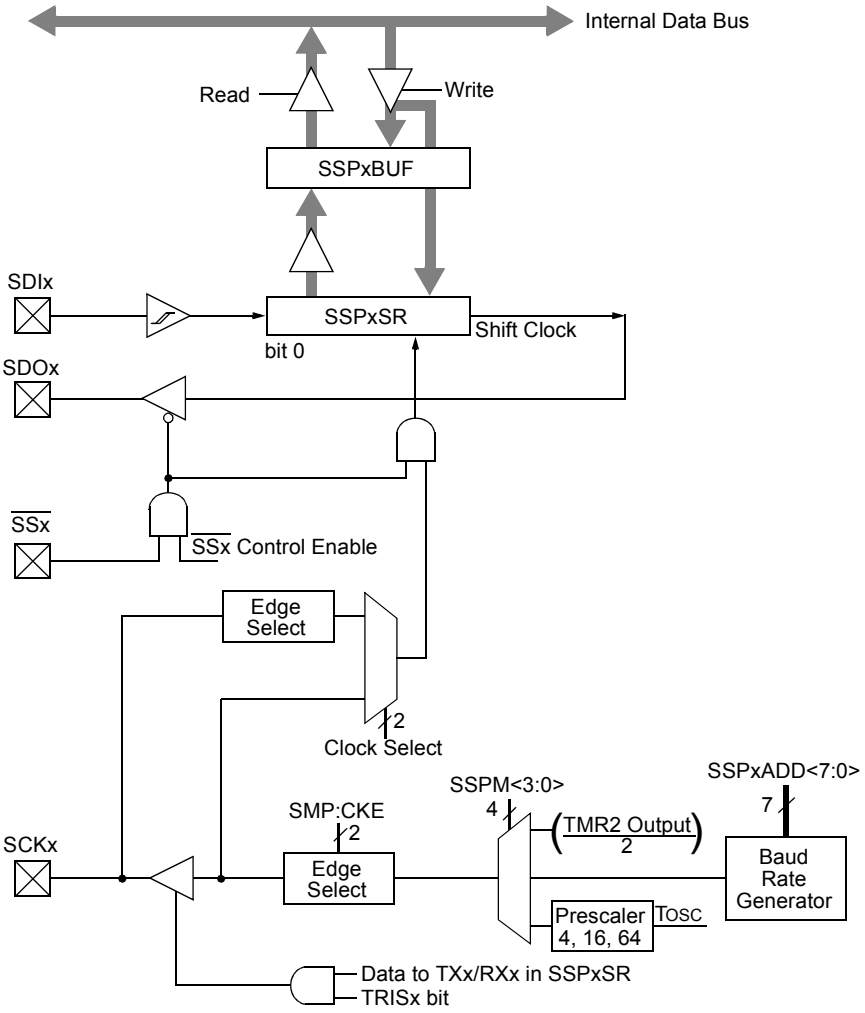
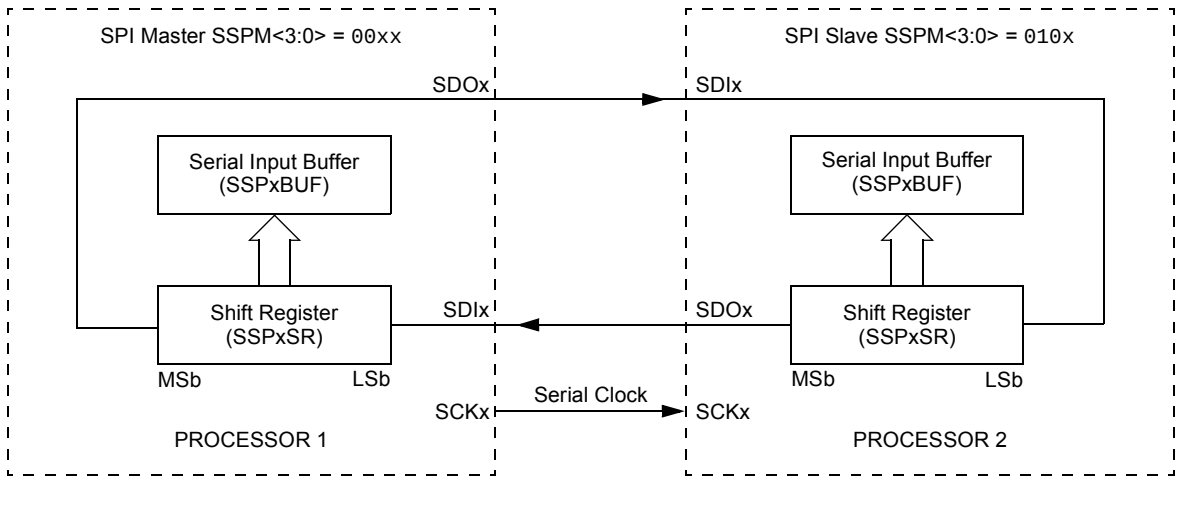


FIGURE 17-1: MSSPx BLOCK DIAGRAM (SPI MODE)



Note: Refer to the device data sheet for pin multiplexing.

FIGURE 17-2: SPI MASTER/SLAVE CONNECTION



18.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Universal Asynchronous Receiver Transmitter, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"UART"** (DS39708).

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in this PIC24F device family. The UART is a full-duplex, asynchronous system that can communicate with peripheral devices, such as personal computers, LIN/J2602, RS-232 and RS-485 interfaces. This module also supports a hardware flow control option with the $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins, and also includes an IrDA® encoder and decoder.

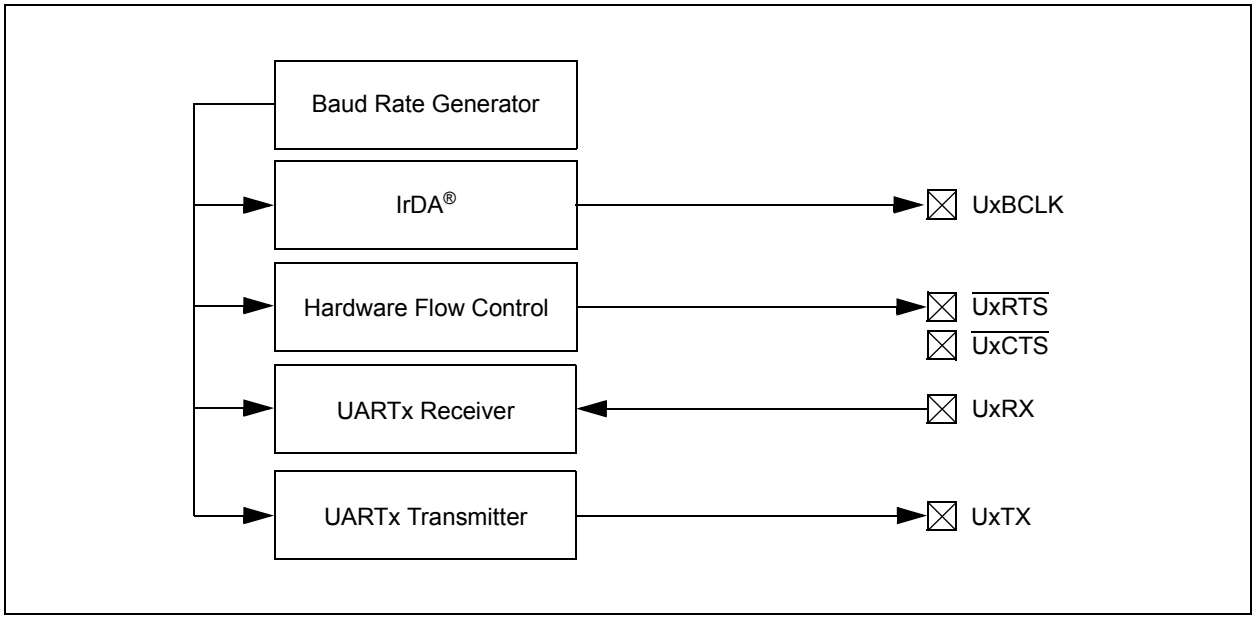
The primary features of the UART module are:

- Full-Duplex, 8-Bit or 9-Bit Data Transmission Through the UxTX and UxRX Pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop bits
- Hardware Flow Control Option with $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ Pins
- Fully Integrated Baud Rate Generator (IBRG) with 16-Bit Prescaler
- Baud Rates Ranging from 1 Mbps to 15 bps at 16 MIPS
- Two-Level Deep, First-In-First-Out (FIFO) Transmit Data Buffer
- Two-Level Deep, FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for 9-Bit mode with Address Detect (9^{th} bit = 1)
- Transmit and Receive Interrupts
- Loopback mode for Diagnostic Support
- Support for Sync and Break Characters
- Supports Automatic Baud Rate Detection
- IrDA Encoder and Decoder Logic
- 16x Baud Clock Output for IrDA® Support

A simplified block diagram of the UART module is shown in Figure 18-1. The UART module consists of these important hardware elements:

- Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 18-1: UARTx SIMPLIFIED BLOCK DIAGRAM



REGISTER 19-5: AD1CSSL: A/D INPUT SCAN SELECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSSL<15:8>(1)							
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSSL<7:6>		—	CSSL<4:0>(1)				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6 **CSSL<15:6>:** A/D Input Pin Scan Selection bits(1)
1 = Corresponding analog channel selected for input scan
0 = Analog channel omitted from input scan

bit 5 **Unimplemented:** Read as ‘0’

bit 4-0 **CSSL<4:0>:** A/D Input Pin Scan Selection bits(1)
1 = Corresponding analog channel selected for input scan
0 = Analog channel omitted from input scan

Note 1: CSSL<12:11,4:2> bits are unimplemented on 14-pin devices.

REGISTER 19-6: ANCFG: ANALOG INPUT CONFIGURATION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	VBGEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as ‘0’

bit 0 **VBGEN:** Internal Band Gap Reference Enable bit
1 = Internal band gap voltage is available as a channel input to the A/D Converter
0 = Band gap is not available to the A/D Converter

24.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16 and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

24.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

24.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

24.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

TABLE 26-1: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 26-2: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 20-Pin PDIP	θ_{JA}	62.4	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SSOP	θ_{JA}	108	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SOIC	θ_{JA}	75	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	80.2	—	°C/W	**1**
Package Thermal Resistance, 20-Pin QFN	θ_{JA}	43	—	°C/W	**1**
Package Thermal Resistance, 28-Pin QFN	θ_{JA}	32	—	°C/W	**1**
Package Thermal Resistance, 14-Pin PDIP	θ_{JA}	62.4	—	°C/W	**1**
Package Thermal Resistance, 14-Pin TSSOP	θ_{JA}	108	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-$_{JA}$ (θ_{JA}) numbers are achieved by package simulations.

TABLE 26-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DC10	V_{DD}	**Supply Voltage**	1.8	—	3.6	V	
DC12	V_{DR}	**RAM Data Retention Voltage(2)**	1.5	—	—	V	
DC16	V_{POR}	**V_{DD} Start Voltage** to Ensure Internal Power-on Reset Signal	V_{SS}	—	0.7	V	
DC17	SV_{DD}	**V_{DD} Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 0.1s 0-2.5V in 60 ms
	V_{BG}	**Band Gap Voltage Reference**	1.14	1.2	1.26	V	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This is the limit to which V_{DD} can be lowered without losing RAM data.

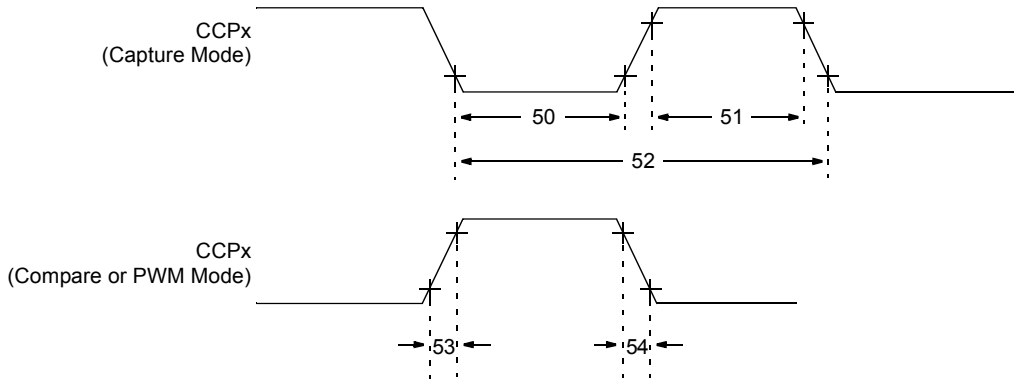
TABLE 26-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})						
DC60	0.01	0.20	µA	-40°C	1.8V	Sleep Mode(2)
	0.03	0.20	µA	+25°C		
	0.06	0.87	µA	+60°C		
	0.20	1.35	µA	+85°C		
	—	8.00	µA	+125ºC		
	0.01	0.54	µA	-40°C	3.3V	
	0.03	0.54	µA	+25°C		
	0.08	1.68	µA	+60°C		
	0.25	2.45	µA	+85°C		
	—	10.00	µA	+125ºC		

Note 1: Data in the Typical column is at 3.3V, +25°C unless otherwise stated.

2: Base I_{PD} is measured with all peripherals and clocks disabled. All I/Os are configured as outputs and set low; PMDx bits are set to '1' and WDT, etc., are all disabled

FIGURE 26-6: CAPTURE/COMPARE/PWM TIMINGS (ECCP1, ECCP2 MODULES)

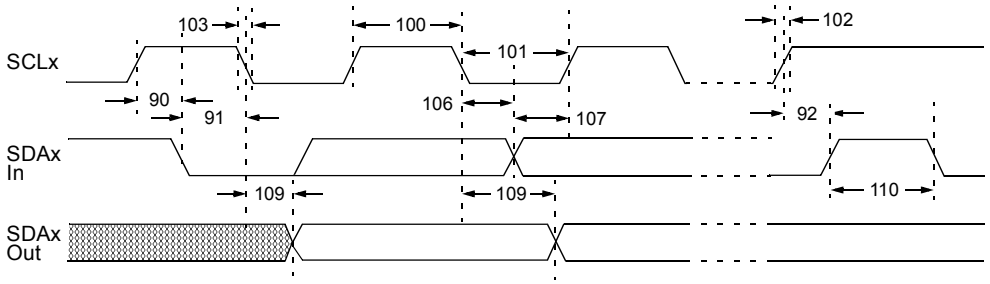


Note: Refer to Figure 26-3 for load conditions.

TABLE 26-26: CAPTURE/COMPARE/PWM REQUIREMENTS (ECCP1, ECCP2 MODULES)

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
50	TccL	CCPx Input Low Time	No Prescaler	0.5 TCY + 20	—	ns	
			With Prescaler	20	—	ns	
51	TccH	CCPx Input High Time	No Prescaler	0.5 TCY + 20	—	ns	
			With Prescaler	20	—	ns	
52	TccP	CCPx Input Period		Greater of: 40 or $\frac{2\,T_{CY} + 40}{N}$	—	ns	N = prescale value (1, 4 or 16)
53	TccR	CCPx Output Fall Time		—	25	ns	
54	TccF	CCPx Output Fall Time		—	25	ns	

FIGURE 26-14: MSSPx I²C™ BUS DATA TIMING



Note: Refer to Figure 26-3 for load conditions.

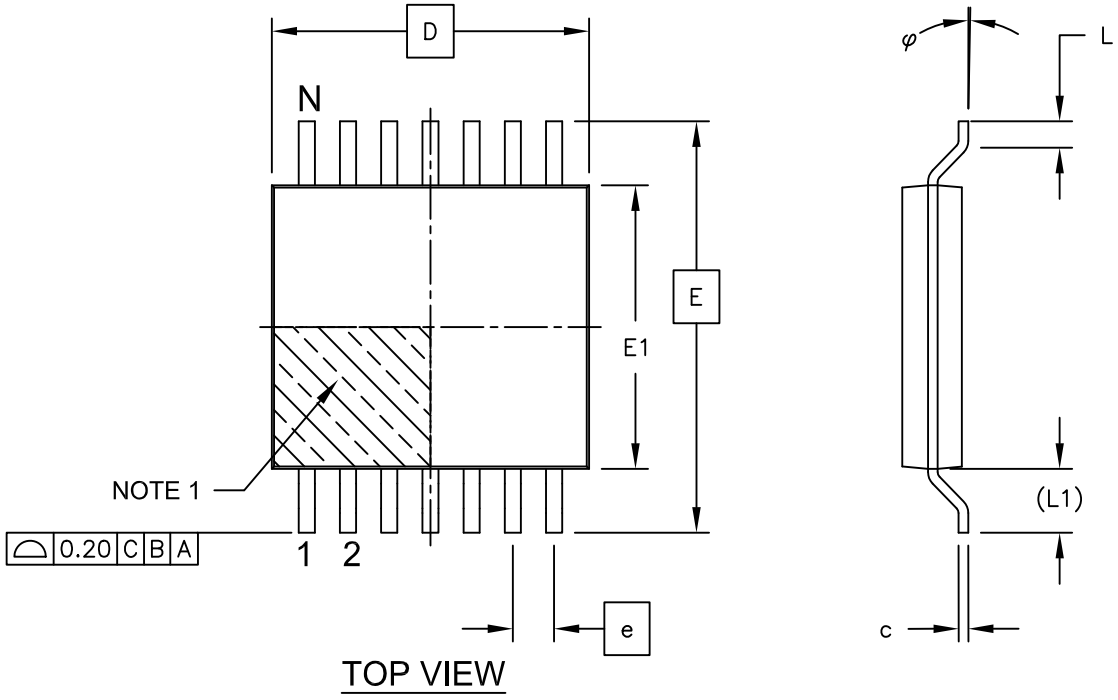
TABLE 26-34: I²C™ BUS DATA REQUIREMENTS (MASTER MODE)

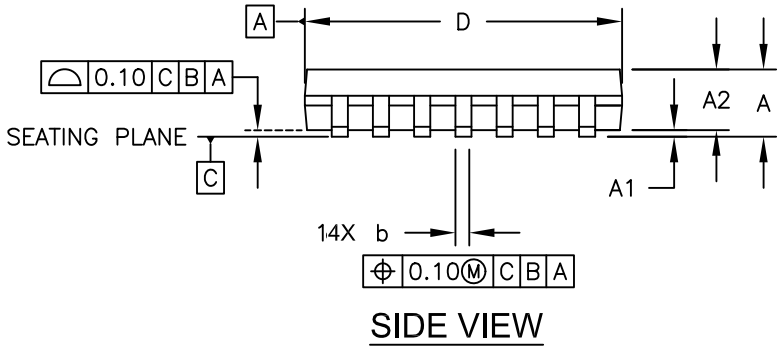
Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 1)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but Parameter 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, Parameter 102 + Parameter 107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCLx line is released.

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

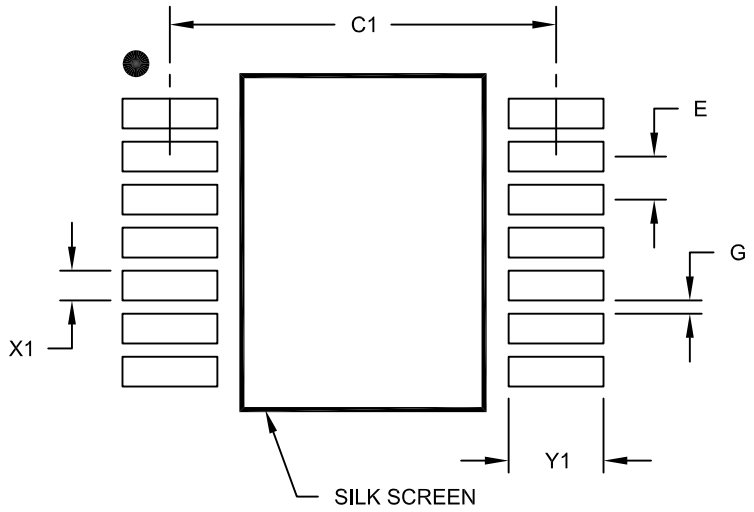




Microchip Technology Drawing C04-087C Sheet 1 of 2

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C1		5.90	
Contact Pad Width (X14)	X1			0.45
Contact Pad Length (X14)	Y1			1.45
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2087A